

CLAIMS

We claim:

1. A power supply layout for an integrated circuit, comprising:

a plurality of power pads;

a plurality of ground pads;

a plurality of conductive wires directly connected to the power pads or the ground pads;

a core circuit electrically connected to the conductive wire to acquire power; and

wherein the integrated circuit is made of a plurality of metal layers, the power pads and the conductive wires connected to the power pads are positioned at the same metal layer, and the ground pads and the conductive wires connected to the ground pads are positioned at the same metal layer.

2. The power supply layout for an integrated circuit of Claim 1, wherein the plurality of conductive wires comprises:

a plurality of first wires; and

a plurality of second wires arranged with the plurality of first wires in a mesh manner.

3. The power supply layout for an integrated circuit of Claim 2, further comprising at least one auxiliary wire electrically connected to the first wires, wherein both ends of the at least one auxiliary wire are not connected to the power pad or the ground pad.

4. The power supply layout for an integrated circuit of Claim 1, wherein the plurality of conductive wires are straight in shape and one end of the conductive wire is electrically connected to the power pad or the ground pad directly.

5. The power supply layout for an integrated circuit of Claim 1, wherein the plurality of conductive wires are straight in shape and both ends of the conductive wire are electrically connected to the power pad or the ground pad around the core circuit directly.

6. The power supply layout for an integrated circuit of Claim 1, wherein the power pads and the ground pads are positioned around the core circuit in a different pitch manner.

7. A power supply layout for an integrated circuit, comprising:

a plurality of power pads;

a plurality of ground pads;

a plurality of first-type conductive wires directly connected to the plurality of power pads;

a plurality of second-type conductive wires directly connected to the plurality of ground pads; and

a core circuit electrically connected to the first-type conductive wires and the second conductive wires for acquiring power;

wherein the integrated circuit is made of a plurality of metal layers, and the first-type conductive wires and the second-type conductive wires are positioned at different metal layers.

8. The power supply layout for an integrated circuit of Claim 7, wherein the plurality of first-type conductive wires comprises:

a plurality of first wires; and

a plurality of second wires arranged with the plurality of first wires in a mesh manner.

9. The power supply layout for an integrated circuit of Claim 8, further comprising at least one auxiliary wire electrically connected to the first wire, wherein both ends of the at least one auxiliary wire are not connected to the power pad or the ground pad.

10. The power supply layout for an integrated circuit of Claim 7, wherein the plurality of first-type conductive wires are straight in shape and one end of the first-type conductive wire is electrically connected to the power pad directly.

11. The power supply layout for an integrated circuit of Claim 7, wherein the plurality of first-type conductive wires are straight in shape and both ends of the first-type conductive wire are electrically connected to the power pad around the core circuit directly.

12. The power supply layout for an integrated circuit of Claim 7, wherein the power pad and the first-type conductive wire are electrically connected to a positive potential, while the ground pad and the second-type conductive wire are electrically connected to a ground potential.

13. The power supply layout for an integrated circuit of Claim 7, wherein the power pads are positioned around the core circuit with different pitches.